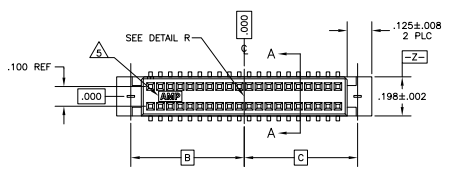
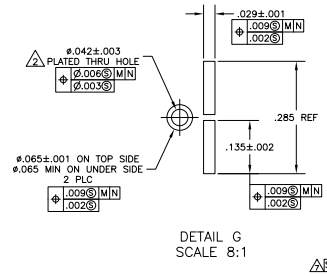
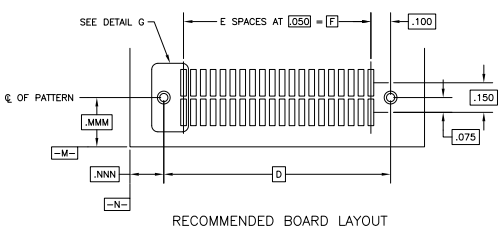


REVISED PER EDD-11-004820		REVISIONS		DATE		BY	
AD	00	TZ	TM		11MM11	RM	HMR

- Δ .00030 GOLD IN LOCALIZED PLATE AREA, .000150 TIN-LEAD ON SOLDER TAILS ALL OVER .000050 NICKEL.
- Δ USE .0465 \pm .0010 DRILLED HOLE (#56 DRILL) FINISH TO BE TIN-LEAD OVER .001 MINIMUM COPPER.
- Δ WINDOWS SHOWN ON SIDE OF HOUSING ARE MOLDERS OPTION.
- Δ REFER TO NO. OF POSN. IN CHART FOR NUMBER OF SURFACES WHICH ARE COPPLANAR.
- Δ AMP LOGO PRESENCE AND LOCATION OPTIONAL.
- Δ .00030 GOLD IN LOCALIZED PLATE AREA, .000150 TIN ON SOLDER TAILS, ALL OVER .000050 NICKEL.
- Δ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



SECTION A-A



DETAIL G SCALE 8:1

F	E	D	C	B	A	NO OF POSN	PART NUMBER
2.450	49	2.650	1.325	1.325	2.544	100	Δ 5-104550-9
1.950	39	2.150	1.075	1.075	2.044	80	Δ 5-104550-8
1.450	29	1.650	.825	.825	1.544	60	Δ 5-104550-7
1.200	24	1.400	.700	.700	1.294	50	Δ 5-104550-6
.950	19	1.150	.575	.575	1.044	40	Δ 5-104550-5
.700	14	.900	.450	.450	.794	30	Δ 5-104550-4
.550	11	.750	.375	.375	.644	24	Δ 5-104550-3
.450	9	.650	.325	.325	.544	20	Δ 5-104550-2
.200	4	.400	.200	.200	.294	10	Δ 5-104550-1
2.450	49	2.650	1.325	1.325	2.544	100	Δ 104550-9
1.950	39	2.150	1.075	1.075	2.044	80	Δ 104550-8
1.450	29	1.650	.825	.825	1.544	60	Δ 104550-7
1.200	24	1.400	.700	.700	1.294	50	Δ 104550-6
.950	19	1.150	.575	.575	1.044	40	Δ 104550-5
.700	14	.900	.450	.450	.794	30	Δ 104550-4
.550	11	.750	.375	.375	.644	24	Δ 104550-3
.450	9	.650	.325	.325	.544	20	Δ 104550-2
.200	4	.400	.200	.200	.294	10	Δ 104550-1

THIS DRAWING IS A CONTROLLED DOCUMENT. SEE H. SKERRED FOR DATE OF REVISION.

REVISIONS:

NO	DATE	DESCRIPTION	BY	CHKD
1	11MM11	REVISED PER EDD-11-004820	TZ	TM

TE Connectivity

RECEPTACLE ASSEMBLY, VERTICAL, DOUBLE ROW, SURFACE MOUNT, AMPHENOL System 50

SIZE: A1 | 00779 | 104550

CUSTOMER DRAWING

DATE: 4-1 | SHEET: 1 | OF: 1